EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	11775	heat with (sink spreader) with (hole throughole passageway via)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L2	7308	L1 and (IC integrated near2 circuit chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L3	7266	L2 and heat near2 (sink spreader) with (hole throughole passageway via)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L4	3385	L3 and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L5	2051	L3 and "257"/$.ccls.	USPAT	OR	ON	2006/08/01 09:50
L6	1584	L3 and (hole throughole passageway via) with (fluid air coolant water)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L7	405	L6 and "257"/$.ccls.	USPAT	OR	ON	2006/08/01 09:50
L8	8	("5029638"| "5466970"| "5506752" | "5559674"| "5706169"| "5991152").PN. OR ("6640882"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:50
L9	52	("2414801"| "3205936"| "3372733" | "3388739"| "3413532"| "3457988" | "4092697"| "4141030"| "4158719" | "4340902"| "4345267"| "4396935" | "4404582"| "4471837"| "4535384" | "4563725"| "4587550"| "4669535" | "4729061"| "4733293"| "4788627" | "4803546"| "4810289"| "4849856" | "4849857"| "4890194"| "4909841" | "4941067"| "4954170"| "4996629" | "5012386"| "5057903"| "5172301" | "5175612"| "5227663"| "5293930" | "5310520"| "5410451"| "5514327" | "5654587"| "5693981").PN. OR ("5963795").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:50

L10	22	("4810289" | "4830820" | "4909841" | "4926242" | "4954170" | "5049184" | "5057903" | "5152959" | "5175612" | "5310520").PN. OR ("5514327"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:50
L11	2946	heat with (sink spreader) with (channel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L12	576	L11 and "257"/$.ccls.	USPAT	OR	ON	2006/08/01 09:50
L13	505	L12 not L7	USPAT	OR	ON	2006/08/01 09:50
L14	264	L12 and heat near2 (sink spreader) near3 channel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L15	364	heat near2 sink with channels near4 air	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L16	5	L15 and "438"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L17	27	("4092697" | "4158719" | "4733293" | "4788627" | "4810289" | "4909841" | "4954170" | "5057903" | "5105259" | "5105429" | "5172301" | "5175612" | "5285350" | "5291064" | "5310520" | "5485037" | "5514327" | "5552634" | "5567986").PN. OR ("5869891"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:50
L18	130	L15 and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L19	2176	"5,701" ",034".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50

L20	2	"5701034".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L21	146	("3564352" | "3838984" | "4074342" | "4105861" | "4168507" | "4410927" | "4461924" | "4480262" | "4594770" | "4680613" | "4701999" | "4737395" | "4769344" | "4773955" | "4835120" | "4868349" | "4872047" | "4888449" | "4890152" | "4891687" | "4943844" | "4949220" | "4974057" | "4975761" | "4994897" | "4994936" | "5041902" | "5102828" | "5172214" | "5202288" | "5235211" | "5278446" | "5294828").PN. OR ("5701034"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:50
L22	1	1998-062476.NRAN.	DERWENT	OR	ON	2006/08/01 09:50
L23	7	"6661087"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L24	2	"6661087".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L25	6	silicone near2 grease with adhesive with heat near2 sink	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L26	49	silicone near2 grease with adhesive and heat near2 sink	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L27	43	L26 not L25	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50

L28	49	silicone near2 grease with adhesive and heat near2 sink	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L29	65	("3846824" | "4326238" | "4626961" | "4709301" | "4764845" | "4782893" | "4869954" | "4931479" | "4965699" | "4971633" | "4974119" | "4979074" | "5060114" | "5137959" | "5194480" | "5213868" | "5225265" | "5298791" | "5321582" | "5518758" | "5661902").PN. OR ("5781412"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:50
L30	27	("4838347" | "4974119" | "5137959" | "5781412" | "5931222" | "5978223" | "5989459" | "6020424" | "6054198" | "6096414" | "6162663" | "6188576" | "6204303" | "6210520" | "6218730" | "6238596" | "6311769" | "6469379").PN. OR ("6597575"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:50
L31	90	("2311526" | "3332055" | "3609104" | "4299715" | "4384610" | "4389340" | "4466483" | "4473113" | "4487856" | "4533685" | "4546411" | "4561011" | "4575432" | "4722960" | "4755249" | "4764845" | "4782893" | "4855002" | "4869954" | "4915167" | "4965699" | "4974119" | "4979074" | "5052481" | "5137959" | "5194480" | "5213868" | "5298791" | "5302344" | "5321882" | "5352731" | "5602221" | "5770318" | "5796582" | "5798171").PN. OR ("6054198").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:50
L32	247	heat with sink with made with (ceramic glass) and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L33	2	"5693981".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L34	2	"5693981".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50

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L35	3	heat with sink with made with (ceramic glass) with improve	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L36	1	heat with sink with made with (ceramic glass)with desirable	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L37	605	heat near2 sink with made with (ceramic glass)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L38	6	heat near2 sink with made with (ceramic glass) with cost	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L39	1036	heat near2 sink with layer with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L40	78	heat near2 sink with made with layer with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L41	11	heat near2 sink with sheet with secured with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L42	45	heat near2 sink with layer with secured with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L43	3	"6730998".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50

L44	2	"20030002260".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L45	2	"5473512".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L46	4	("6514792" "6713856").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L47	149	and$1j$1r.xa.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L48	2	("6548832").URPN.	USPAT	OR	ON	2006/08/01 09:50
L49	15	("20030020399" | "4013915" | "4826271" | "4935665" | "5177593" | "5226723" | "5294487" | "5298768" | "5534718" | "6121637" | "6274890" | "6429464" | "6483161" | "6501103" | "6548832").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:50
L50	4	("6677222" "6506669").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L51	3	("6677222").URPN.	USPAT	OR	ON	2006/08/01 09:50
L52	6	("4876360" | "4897360" | "5077233" | "5264072" | "5663077" | "5756364").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:50
L53	1	2000-117261.NRAN.	DERWENT	OR	ON	2006/08/01 09:50
L54	1	2001-524823.NRAN.	DERWENT	OR	ON	2006/08/01 09:50
L55	1	"6730998".pn.	USPAT	OR	ON	2006/08/01 09:50

L56	103	("4863538"|"4944817"|"5017753"|"5 088047"|"5132143"|"5155321"|"515 5324"|"5156697"|"5173220"|"51821 70"|"5252264"|"5264061"|"5278442" |"5284695"|"5304329"|"5316580"|"5 325265"|"5332051"|"5342919"|"535 2405"|"5385780"|"5484314"|"55278 77"|"5648450"|"5672312"|"5673258" |"5705117"|"5733497"|"5749041"|"5 814536"|"5817206"|"5900670"|"598 1085"|"6015722"|"6296493"|"64688 91"|"4526646"|"4543659"|"4736437" |"4899921"|"5059559"|"5113565"|"5 145099"|"5238174"|"5288698"|"543 0666"|"5463227"|"5471310"|"55066 84"|"5516023"|"5516026"|"5644245").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L57	8	("6259962"|"6268584"|"6391251"|"6 251488").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L58	8	("5645937"|"6111313"|"6274922"|"6 457515").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L59	4	("5693981"|"6175497").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L60	123	L56 L57 L58 L59	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L61	112	fin with heat with sink with improve	USPAT	OR	ON	2006/08/01 09:50
L62	77	("4047198" | "4561011" | "4612601" | "4748538").PN. OR ("5291064"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:50
L63	1379	(257/713).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 09:50

L64	1488	(257/714).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 09:50
L65	739	(257/715).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 09:50
L66	293	(257/716).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 09:50
L67	2381	L64 L65 L66	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L68	932	L67 and air	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L69	76	L68 and coil	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L70	77	("4047198" | "4561011" | "4612601" | "4748538").PN. OR ("5291064"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:50
L71	27	("4092697" | "4158719" | "4733293" | "4788627" | "4810289" | "4909841" | "4954170" | "5057903" | "5105259" | "5105429" | "5172301" | "5175612" | "5285350" | "5291064" | "5310520" | "5485037" | "5514327" | "5552634" | "5567986").PN. OR ("5869891"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:50
L72	2	"5,693,981".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50

L73	11	heat adj sink with sintered with binder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L74	27	heat adj sink same sintered with binder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L75	16	L74 not L73	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L76	66	heat adj sink same sinter$4 with binder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L77	55	L76 not L73	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L78	2	"5,814,536".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L79	8	heat with sink with layered with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L80	1663	heat with sink same layer$3 with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L81	1636	heat adj sink same layer$3 with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50

L82	1035	heat adj sink with layer$3 with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L83	872	heat adj sink with layer$3 with adhesive and (semiconductor IC chip die wafer integrated adj cirucit silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L84	21	heat adj sink with layer$3 with adhesive with improve and (semiconductor IC chip die wafer integrated adj cirucit silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L85	1663	heat adj sink with multi with layer$3 with adhesive with adn L80	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L86	34	heat adj sink with multi with layer$3 with adhesive and L80	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L87	1	multi with layer$3 near3 heat adj sink with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L88	34	multi with layer$3 with heat adj sink with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L89	0	L88 not L86	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L90	1663	heat adj sink near3 layer$3 with adhesive with adn L80	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50

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L91	404	heat adj sink near3 layer$3 with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L92	297	heat adj sink near3 layer$3 with adhesive	US-PGPUB; USPAT	OR	ON	2006/08/01 09:50
L93	199	heat adj sink near3 layer$3 with adhesive	USPAT	OR	ON	2006/08/01 09:50
L94	0	integrated with Cirucit with processor with waveguide	USPAT	OR	ON	2006/08/01 09:50
L95	63	(IC chip die wafer integrated adj circuit semiconductor) same processor with waveguide	USPAT	OR	ON	2006/08/01 09:50
L96	6	(IC chip die wafer integrated adj circuit semiconductor)and processor with coplanar near2 waveguide	USPAT	OR	ON	2006/08/01 09:50
L97	8	(IC chip die wafer integrated adj circuit semiconductor)and processor same coplanar near2 waveguide	USPAT	OR	ON	2006/08/01 09:50
L98	65	(IC chip die wafer integrated adj circuit semiconductor)and processor and coplanar near2 waveguide	USPAT	OR	ON	2006/08/01 09:50
L99	9	("5548150" | "5736749" | "5773353" | "6013933" | "6021675" | "6153489" | "6376859" | "6407441" | "6452249").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:50
L100	10	("3948583" | "4912533" | "5054871" | "5182787" | "5185830" | "5282071" | "5522005" | "5621837" | "5721801").PN. OR ("6108477"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:50
L101	149	integrated adj circuit with commonly with processor	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:50
L102	86	integrated adj circuit with commonly with processor	USPAT; USOCR	OR	ON	2006/08/01 09:50
L103	3	signal with coplanar with microprocessor	USPAT; USOCR	OR	ON	2006/08/01 09:50
L104	0	processor with coplannar with waveguide	USPAT; USOCR	OR	ON	2006/08/01 09:50
L105	6	processor with coplanar with waveguide	USPAT; USOCR	OR	ON	2006/08/01 09:50
L106	86	processor with waveguide with system	USPAT; USOCR	OR	ON	2006/08/01 09:50
L107	125	coplanar adj waveguide and (processor or microprocessor)	USPAT; USOCR	OR	ON	2006/08/01 09:50
L108	1	"4,575,700".pn.	USPAT; USOCR	OR	ON	2006/08/01 09:50

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L109	2	("5895971").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L110	134	("4526646"|"4543659"|"4736437"|"4863538"|"4899921"|"4944817"|"5017753"|"5059559"|"5088047"|"5113565"|"5132143"|"5145099"|"5155321"|"5155324"|"5156697"|"5173220"|"5182170"|"5238174"|"5252264"|"5264061"|"5278442"|"5284695"|"5288698"|"5304329"|"5316580"|"5325265"|"5332051"|"5342919"|"5352405"|"5385780"|"5430666"|"5463227"|"5471310"|"5484314"|"5506684"|"5516023"|"5516026"|"5527877"|"5644245"|"5645937"|"5648450"|"5672312"|"5673258"|"5693981"|"5705117"|"5733497"|"5749041"|"5814536"|"5814536"|"5817206"|"5895971"|"5900670"|"5981085"|"6015722"|"6019165"|"6111313"|"6175497"|"6251488"|"6259962"|"6268584"|"6274922"|"6296493"|"6391251"|"6457515"|"6468891"|"6529379"|"6658314"|"6730998").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L111	0	("4526646"|"4543659"|"4736437"|"4863538"|"4899921"|"4944817"|"5017753"|"5059559"|"5088047"|"5113565"|"5132143"|"5145099"|"5155321"|"5155324"|"5156697"|"5173220"|"5182170"|"5238174"|"5252264"|"5264061"|"5278442"|"5284695"|"5288698"|"5304329"|"5316580"|"5325265"|"5332051"|"5342919"|"5352405"|"5385780"|"5430666"|"5463227"|"5471310"|"5484314"|"5506684"|"5516023"|"5516026"|"5527877"|"5644245"|"5645937"|"5648450"|"5672312"|"5673258"|"5693981"|"5705117"|"5733497"|"5749041"|"5814536"|"5817206"|"5895971"|"5900670"|"5981085"|"6015722"|"6019165"|"6111313"|"6175497"|"6251488"|"6259962"|"6268584"|"6274922"|"6296493"|"6391251"|"6457515"|"6468891"|"6529379"|"6658314"|"6730998").PN.	US-PGPUB	OR	ON	2006/08/01 09:50

L112	67	("4526646"|"4543659"|"4736437"|"4863538"|"4899921"|"4944817"|"5017753"|"5059559"|"5088047"|"5113565"|"5132143"|"5145099"|"5155321"|"5155324"|"5156697"|"5173220"|"5182170"|"5238174"|"5252264"|"5264061"|"5278442"|"5284695"|"5288698"|"5304329"|"5316580"|"5325265"|"5332051"|"5342919"|"5352405"|"5385780"|"5430666"|"5463227"|"5471310"|"5484314"|"5506684"|"5516023"|"5516026"|"5527877"|"5644245"|"5645937"|"5648450"|"5672312"|"5673258"|"5693981"|"5705117"|"5733497"|"5749041"|"5814536"|"5814536"|"5817206"|"5895971"|"5900670"|"5981085"|"6015722"|"6019165"|"6111313"|"6175497"|"6251488"|"6259962"|"6268584"|"6274922"|"6296493"|"6391251"|"6457515"|"6468891"|"6529379"|"6658314"|"6730998").PN.	USPAT	OR	ON	2006/08/01 09:50
L113	11775	heat with (sink spreader) with (hole throughole passageway via)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L114	7308	L113 and (IC integrated near2 circuit chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L115	7266	L114 and heat near2 (sink spreader) with (hole throughole passageway via)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L116	3385	L115 and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L117	1584	L115 and (hole throughole passageway via) with (fluid air coolant water)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50

L118	2946	heat with (sink spreader) with (channel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:50
L119	576	L118 and "257"/$.ccls.	USPAT	OR	ON	2006/08/01 09:50
L120	2176	"5,701" ",034".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L121	7	"6661087"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L122	49	silicone near2 grease with adhesive and heat near2 sink	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L123	605	heat near2 sink with made with (ceramic glass)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L124	1036	heat near2 sink with layer with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L125	3	("6677222").URPN.	USPAT	OR	ON	2006/08/01 09:51
L126	481	finger with tooth with brush	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L127	10936	oral with b	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51

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L128	611	L127 and finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L129	0	L128 and figer with brushing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L130	0	oral near2 b and finger.ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L131	8	("6259962"|"6268584"|"6391251"|"6251488").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L132	8	("5645937"|"6111313"|"6274922"|"6457515").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L133	4	("5693981"|"6175497").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L134	1379	(257/713).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 09:51
L135	1488	(257/714).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 09:51
L136	739	(257/715).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 09:51

EAST Search History

L137	293	(257/716).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 09:51
L138	2381	L135 L136 L137	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L139	66	heat adj sink same sinter$4 with binder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L140	1663	heat with sink same layer$3 with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L141	1636	heat adj sink same layer$3 with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L142	1035	heat adj sink with layer$3 with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L143	872	heat adj sink with layer$3 with adhesive and (semiconductor IC chip die wafer integrated adj cirucit silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L144	1663	heat adj sink with multi with layer$3 with adhesive with adn L140	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L145	34	multi with layer$3 with heat adj sink with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51

L146	34	heat adj sink with multi with layer$3 with adhesive and L140	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L147	0	L145 not L146	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L148	1663	heat adj sink near3 layer$3 with adhesive with adn L140	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L149	0	integrated with Cirucit with processor with waveguide	USPAT	OR	ON	2006/08/01 09:51
L150	8	(IC chip die wafer integrated adj circuit semiconductor)and processor same coplanar near2 waveguide	USPAT	OR	ON	2006/08/01 09:51
L151	149	integrated adj circuit with commonly with processor	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51
L152	0	processor with coplannar with waveguide	USPAT; USOCR	OR	ON	2006/08/01 09:51
L153	0	("4526646"|"4543659"|"4736437"|"4863538"|"4899921"|"4944817"|"5017753"|"5059559"|"5088047"|"5113565"|"5132143"|"5145099"|"5155321"|"5155324"|"5156697"|"5173220"|"5182170"|"5238174"|"5252264"|"5264061"|"5278442"|"5284695"|"5288698"|"5304329"|"5316580"|"5325265"|"5332051"|"5342919"|"5352405"|"5385780"|"5430666"|"5463227"|"5471310"|"5484314"|"5506684"|"5516023"|"5516026"|"5527877"|"5644245"|"5645937"|"5648450"|"5672312"|"5673258"|"5693981"|"5705117"|"5733497"|"5749041"|"5814536"|"5814536"|"5817206"|"5895971"|"5900670"|"5981085"|"6015722"|"6019165"|"6111313"|"6175497"|"6251488"|"6259962"|"6268584"|"6274922"|"6296493"|"6391251"|"6457515"|"6468891"|"6529379"|"6658314"|"6730998"). PN.	US-PGPUB	OR	ON	2006/08/01 09:51
L154	1	1998-062476.NRAN.	DERWENT	OR	ON	2006/08/01 09:51

L155	1	heat with sink with made with (ceramic glass)with desirable	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L156	1	2000-117261.NRAN.	DERWENT	OR	ON	2006/08/01 09:51
L157	1	2001-524823.NRAN.	DERWENT	OR	ON	2006/08/01 09:51
L158	1	"6730998".pn.	USPAT	OR	ON	2006/08/01 09:51
L159	1	multi with layer$3 near3 heat adj sink with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L160	1	"4,575,700".pn.	USPAT; USOCR	OR	ON	2006/08/01 09:51
L161	8	("5029638" | "5466970" | "5506752" | "5559674" | "5706169" | "5991152").PN. OR ("6640882"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51
L162	52	("2414801" | "3205936" | "3372733" | "3388739" | "3413532" | "3457988" | "4092697" | "4141030" | "4158719" | "4340902" | "4345267" | "4396935" | "4404582" | "4471837" | "4535384" | "4563725" | "4587550" | "4669535" | "4729061" | "4733293" | "4788627" | "4803546" | "4810289" | "4849856" | "4849857" | "4890194" | "4909841" | "4941067" | "4954170" | "4996629" | "5012386" | "5057903" | "5172301" | "5175612" | "5227663" | "5293930" | "5310520" | "5410451" | "5514327" | "5654587" | "5693981").PN. OR ("5963795").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51
L163	22	("4810289" | "4830820" | "4909841" | "4926242" | "4954170" | "5049184" | "5057903" | "5152959" | "5175612" | "5310520").PN. OR ("5514327"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51
L164	364	heat near2 sink with channels near4 air	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L165	5	L164 and "438"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51

L166	27	("4092697"| "4158719"| "4733293"| "4788627"| "4810289"| "4909841"| "4954170"| "5057903"| "5105259"| "5105429"| "5172301"| "5175612"| "5285350"| "5291064"| "5310520"| "5485037"| "5514327"| "5552634"| "5567986").PN. OR ("5869891"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51
L167	2	"5701034".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L168	2	"6661087".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L169	6	silicone near2 grease with adhesive with heat near2 sink	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L170	43	L122 not L169	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L171	49	silicone near2 grease with adhesive and heat near2 sink	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L172	65	("3846824"| "4326238"| "4626961"| "4709301"| "4764845"| "4782893"| "4869954"| "4931479"| "4965699"| "4971633"| "4974119"| "4979074"| "5060114"| "5137959"| "5194480"| "5213868"| "5225265"| "5298791"| "5321582"| "5518758"| "5661902").PN. OR ("5781412"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51
L173	27	("4838347"| "4974119"| "5137959"| "5781412"| "5931222"| "5978223"| "5989459"| "6020424"| "6054198"| "6096414"| "6162663"| "6188576"| "6204303"| "6210520"| "6218730"| "6238596"| "6311769"| "6469379").PN. OR ("6597575"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51

L174	90	("2311526" | "3332055" | "3609104" | "4299715" | "4384610" | "4389340" | "4466483" | "4473113" | "4487856" | "4533685" | "4546411" | "4561011" | "4575432" | "4722960" | "4755249" | "4764845" | "4782893" | "4855002" | "4869954" | "4915167" | "4965699" | "4974119" | "4979074" | "5052481" | "5137959" | "5194480" | "5213868" | "5298791" | "5302344" | "5321882" | "5352731" | "5602221" | "5770318" | "5796582" | "5798171").PN. OR ("6054198").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51
L175	2	"5693981".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L176	2	"5693981".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L177	3	heat with sink with made with (ceramic glass) with improve	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L178	6	heat near2 sink with made with (ceramic glass) with cost	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L179	78	heat near2 sink with made with layer with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L180	11	heat near2 sink with sheet with secured with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L181	45	heat near2 sink with layer with secured with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51

L182	3	"6730998".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L183	2	"20030002260".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L184	2	"5473512".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L185	4	("6514792" "6713856").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L186	2	("6548832").URPN.	USPAT	OR	ON	2006/08/01 09:51
L187	15	("20030020399" | "4013915" | "4826271" | "4935665" | "5177593" | "5226723" | "5294487" | "5298768" | "5534718" | "6121637" | "6274890" | "6429464" | "6483161" | "6501103" | "6548832").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51
L188	4	("6677222" "6506669").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L189	6	("4876360" | "4897360" | "5077233" | "5264072" | "5663077" | "5756364").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51
L190	112	("5701034").URPN.	USPAT	OR	ON	2006/08/01 09:51
L191	17	(US-5278446-$ or US-5514327-$ or US-5597034-$ or US-5661638-$ or US-5693981-$ or US-5963795-$ or US-6054198-$ or US-6175497-$ or US-6583438-$ or US-6597575-$ or US-6617199-$ or US-6620515-$ or US-6631756-$ or US-6640882-$ or US-6644395-$ or US-6659169-$ or US-6686532-$ or US-6740972-$ or US-6778394-$ or US-6783692-$ or US-6815486-$).did.	USPAT	OR	ON	2006/08/01 09:51

L192	77	("4047198"| "4561011"| "4612601" | "4748538").PN. OR ("5291064"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51
L193	932	L138 and air	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L194	76	L193 and coil	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L195	77	("4047198"| "4561011"| "4612601" | "4748538").PN. OR ("5291064"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51
L196	27	("4092697"| "4158719"| "4733293" | "4788627"| "4810289"| "4909841" | "4954170"| "5057903"| "5105259" | "5105429"| "5172301"| "5175612" | "5285350"| "5291064"| "5310520" | "5485037"| "5514327"| "5552634" | "5567986").PN. OR ("5869891"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51
L197	2	"5,693,981".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L198	11	heat adj sink with sintered with binder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L199	27	heat adj sink same sintered with binder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L200	16	L199 not L198	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51

L201	55	L139 not L198	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L202	2	"5,814,536".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L203	8	heat with sink with layered with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L204	21	heat adj sink with layer$3 with adhesive with improve and (semiconductor IC chip die wafer integrated adj cirucit silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L205	63	(IC chip die wafer integrated adj circuit semiconductor) same processor with waveguide	USPAT	OR	ON	2006/08/01 09:51
L206	6	(IC chip die wafer integrated adj circuit semiconductor)and processor with coplanar near2 waveguide	USPAT	OR	ON	2006/08/01 09:51
L207	65	(IC chip die wafer integrated adj circuit semiconductor)and processor and coplanar near2 waveguide	USPAT	OR	ON	2006/08/01 09:51
L208	9	("5548150" | "5736749" | "5773353" | "6013933" | "6021675" | "6153489" | "6376859" | "6407441" | "6452249").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51
L209	10	("3948583" | "4912533" | "5054871" | "5182787" | "5185830" | "5282071" | "5522005" | "5621837" | "5721801").PN. OR ("6108477"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51
L210	86	integrated adj circuit with commonly with processor	USPAT; USOCR	OR	ON	2006/08/01 09:51
L211	3	signal with coplanar with microprocessor	USPAT; USOCR	OR	ON	2006/08/01 09:51
L212	6	processor with coplanar with waveguide	USPAT; USOCR	OR	ON	2006/08/01 09:51
L213	86	processor with waveguide with system	USPAT; USOCR	OR	ON	2006/08/01 09:51
L214	125	coplanar adj waveguide and (processor or microprocessor)	USPAT; USOCR	OR	ON	2006/08/01 09:51

L215	2	("5895971").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L216	67	("4526646"|"4543659"|"4736437"|"4 863538"|"4899921"|"4944817"|"501 7753"|"5059559"|"5088047"|"51135 65"|"5132143"|"5145099"|"5155321" |"5155324"|"5156697"|"5173220"|"5 182170"|"5238174"|"5252264"|"526 4061"|"5278442"|"5284695"|"52886 98"|"5304329"|"5316580"|"5325265" |"5332051"|"5342919"|"5352405"|"5 385780"|"5430666"|"5463227"|"547 1310"|"5484314"|"5506684"|"55160 23"|"5516026"|"5527877"|"5644245" |"5645937"|"5648450"|"5672312"|"5 673258"|"5693981"|"5705117"|"573 3497"|"5749041"|"5814536"|"58145 36"|"5817206"|"5895971"|"5900670" |"5981085"|"6015722"|"6019165"|"6 111313"|"6175497"|"6251488"|"625 9962"|"6268584"|"6274922"|"62964 93"|"6391251"|"6457515"|"6468891" |"6529379"|"6658314"|"6730998"). PN.	USPAT	OR	ON	2006/08/01 09:51
L217	130	L164 and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L218	146	("3564352" | "3838984" | "4074342" | "4105861" | "4168507" | "4410927" | "4461924" | "4480262" | "4594770" | "4680613" | "4701999" | "4737395" | "4769344" | "4773955" | "4835120" | "4868349" | "4872047" | "4888449" | "4890152" | "4891687" | "4943844" | "4949220" | "4974057" | "4975761" | "4994897" | "4994936" | "5041902" | "5102828" | "5172214" | "5202288" | "5235211" | "5278446" | "5294828").PN. OR ("5701034"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51
L219	149	and$1j$1r.xa.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51

L220	103	("4863538""4944817""5017753""5 088047""5132143""5155321""515 5324""5156697""5173220""51821 70""5252264""5264061""5278442" "5284695""5304329""5316580""5 325265""5332051""5342919""535 2405""5385780""5484314""55278 77""5648450""5672312""5673258" "5705117""5733497""5749041""5 814536""5817206""5900670""598 1085""6015722""6296493""64688 91""4526646""4543659""4736437" "4899921""5059559""5113565""5 145099""5238174""5288698""543 0666""5463227""5471310""55066 84""5516023""5516026""5644245").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L221	123	L220 L131 L132 L133	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L222	112	fin with heat with sink with improve	USPAT	OR	ON	2006/08/01 09:51
L223	199	heat adj sink near3 layer$3 with adhesive	USPAT	OR	ON	2006/08/01 09:51
L224	134	("4526646""4543659""4736437""4 863538""4899921""4944817""501 7753""5059559""5088047""51135 65""5132143""5145099""5155321" "5155324""5156697""5173220""5 182170""5238174""5252264""526 4061""5278442""5284695""52886 98""5304329""5316580""5325265" "5332051""5342919""5352405""5 385780""5430666""5463227""547 1310""5484314""5506684""55160 23""5516026""5527877""5644245" "5645937""5648450""5672312""5 673258""5693981""5705117""573 3497""5749041""5814536""58145 36""5817206""5895971""5900670" "5981085""6015722""6019165""6 111313""6175497""6251488""625 9962""6268584""6274922""62964 93""6391251""6457515""6468891" "6529379""6658314""6730998"). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L225	264	L119 and heat near2 (sink spreader) near3 channel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51

L226	247	heat with sink with made with (ceramic glass) and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L227	297	heat adj sink near3 layer$3 with adhesive	US-PGPUB; USPAT	OR	ON	2006/08/01 09:51
L228	405	L117 and "257"/$.ccls.	USPAT	OR	ON	2006/08/01 09:51
L229	404	heat adj sink near3 layer$3 with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L230	505	L119 not L228	USPAT	OR	ON	2006/08/01 09:51
L231	611	L127 and finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L232	2051	L115 and "257"/$.ccls.	USPAT	OR	ON	2006/08/01 09:51
L233	11775	heat with (sink spreader) with (hole throughole passageway via)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L234	7308	L233 and (IC integrated near2 circuit chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L235	7266	L234 and heat near2 (sink spreader) with (hole throughole passageway via)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L236	3385	L235 and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L237	1584	L235 and (hole throughole passageway via) with (fluid air coolant water)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51

L238	2946	heat with (sink spreader) with (channel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L239	576	L238 and "257"/$.ccls.	USPAT	OR	ON	2006/08/01 09:51
L240	2176	"5,701" ",034".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L241	7	"6661087"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L242	49	silicone near2 grease with adhesive and heat near2 sink	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L243	605	heat near2 sink with made with (ceramic glass)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L244	1036	heat near2 sink with layer with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L245	3	("6677222").URPN.	USPAT	OR	ON	2006/08/01 09:51
L246	481	finger with tooth with brush	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L247	10936	oral with b	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51

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L248	611	L247 and finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L249	0	L248 and figer with brushing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L250	0	oral near2 b and finger.ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L251	8	("6259962"|"6268584"|"6391251"|"6251488").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L252	8	("5645937"|"6111313"|"6274922"|"6457515").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L253	4	("5693981"|"6175497").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L254	1379	(257/713).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 09:51
L255	1488	(257/714).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 09:51
L256	739	(257/715).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 09:51

L257	293	(257/716).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 09:51
L258	2381	L255 L256 L257	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L259	66	heat adj sink same sinter$4 with binder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L260	1663	heat with sink same layer$3 with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L261	1636	heat adj sink same layer$3 with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L262	1035	heat adj sink with layer$3 with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L263	872	heat adj sink with layer$3 with adhesive and (semiconductor IC chip die wafer integrated adj cirucit silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L264	1663	heat adj sink with multi with layer$3 with adhesive with adn L260	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L265	34	multi with layer$3 with heat adj sink with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51

L266	34	heat adj sink with multi with layer$3 with adhesive and L260	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L267	0	L265 not L266	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L268	1663	heat adj sink near3 layer$3 with adhesive with adn L260	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L269	0	integrated with Cirucit with processor with waveguide	USPAT	OR	ON	2006/08/01 09:51
L270	8	(IC chip die wafer integrated adj circuit semiconductor)and processor same coplanar near2 waveguide	USPAT	OR	ON	2006/08/01 09:51
L271	149	integrated adj circuit with commonly with processor	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:51
L272	0	processor with coplannar with waveguide	USPAT; USOCR	OR	ON	2006/08/01 09:51
L273	0	("4526646"|"4543659"|"4736437"|"4863538"|"4899921"|"4944817"|"5017753"|"5059559"|"5088047"|"5113565"|"5132143"|"5145099"|"5155321"|"5155324"|"5156697"|"5173220"|"5182170"|"5238174"|"5252264"|"5264061"|"5278442"|"5284695"|"5288698"|"5304329"|"5316580"|"5325265"|"5332051"|"5342919"|"5352405"|"5385780"|"5430666"|"5463227"|"5471310"|"5484314"|"5506684"|"5516023"|"5516026"|"5527877"|"5644245"|"5645937"|"5648450"|"5672312"|"5673258"|"5693981"|"5705117"|"5733497"|"5749041"|"5814536"|"5814536"|"5817206"|"5895971"|"5900670"|"5981085"|"6015722"|"6019165"|"6111313"|"6175497"|"6251488"|"6259962"|"6268584"|"6274922"|"6296493"|"6391251"|"6457515"|"6468891"|"6529379"|"6658314"|"6730998"). PN.	US-PGPUB	OR	ON	2006/08/01 09:51

L274	11775	heat with (sink spreader) with (hole throughole passageway via)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L275	7308	L274 and (IC integrated near2 circuit chip die wafer semiconductor)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L276	7266	L275 and heat near2 (sink spreader) with (hole throughole passageway via)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L277	3385	L276 and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L278	1584	L276 and (hole throughole passageway via) with (fluid air coolant water)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L279	2946	heat with (sink spreader) with (channel)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L280	576	L279 and "257"/$.ccls.	USPAT	OR	ON	2006/08/01 09:51
L281	2176	"5,701" ",034".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:51
L282	7	"6661087"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L283	49	silicone near2 grease with adhesive and heat near2 sink	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52

L284	605	heat near2 sink with made with (ceramic glass)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L285	1036	heat near2 sink with layer with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L286	3	("6677222").URPN.	USPAT	OR	ON	2006/08/01 09:52
L287	481	finger with tooth with brush	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L288	10936	oral with b	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L289	611	L288 and finger	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L290	0	L289 and figer with brushing	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L291	0	oral near2 b and finger.ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L292	8	("6259962"|"6268584"|"6391251"|"6251488").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L293	8	("5645937"|"6111313"|"6274922"|"6457515").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52

L294	4	("5693981"|"6175497").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L295	1379	(257/713).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 09:52
L296	1488	(257/714).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 09:52
L297	739	(257/715).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 09:52
L298	293	(257/716).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/08/01 09:52
L299	2381	L296 L297 L298	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L300	66	heat adj sink same sinter$4 with binder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L301	1663	heat with sink same layer$3 with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L302	1636	heat adj sink same layer$3 with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52

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L303	1035	heat adj sink with layer$3 with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L304	872	heat adj sink with layer$3 with adhesive and (semiconductor IC chip die wafer integrated adj cirucit silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L305	1663	heat adj sink with multi with layer$3 with adhesive with adn L301	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L306	34	multi with layer$3 with heat adj sink with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L307	34	heat adj sink with multi with layer$3 with adhesive and L301	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L308	0	L306 not L307	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L309	1663	heat adj sink near3 layer$3 with adhesive with adn L301	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L310	0	integrated with Cirucit with processor with waveguide	USPAT	OR	ON	2006/08/01 09:52
L311	8	(IC chip die wafer integrated adj circuit semiconductor)and processor same coplanar near2 waveguide	USPAT	OR	ON	2006/08/01 09:52
L312	149	integrated adj circuit with commonly with processor	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L313	0	processor with coplannar with waveguide	USPAT; USOCR	OR	ON	2006/08/01 09:52

L314	0	("4526646"	"4543659"	"4736437"	"4 863538"	"4899921"	"4944817"	"501 7753"	"5059559"	"5088047"	"51135 65"	"5132143"	"5145099"	"5155321"	"5155324"	"5156697"	"5173220"	"5 182170"	"5238174"	"5252264"	"526 4061"	"5278442"	"5284695"	"52886 98"	"5304329"	"5316580"	"5325265"	"5332051"	"5342919"	"5352405"	"5 385780"	"5430666"	"5463227"	"547 1310"	"5484314"	"5506684"	"55160 23"	"5516026"	"5527877"	"5644245"	"5645937"	"5648450"	"5672312"	"5 673258"	"5693981"	"5705117"	"573 3497"	"5749041"	"5814536"	"58145 36"	"5817206"	"5895971"	"5900670"	"5981085"	"6015722"	"6019165"	"6 111313"	"6175497"	"6251488"	"625 9962"	"6268584"	"6274922"	"62964 93"	"6391251"	"6457515"	"6468891"	"6529379"	"6658314"	"6730998"). PN.	US-PGPUB	OR	ON	2006/08/01 09:52
L315	364	heat near2 sink with channels near4 air	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L316	932	L299 and air	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L317	1	1998-062476.NRAN.	DERWENT	OR	ON	2006/08/01 09:52
L318	1	heat with sink with made with (ceramic glass)with desirable	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L319	1	2000-117261.NRAN.	DERWENT	OR	ON	2006/08/01 09:52
L320	1	2001-524823.NRAN.	DERWENT	OR	ON	2006/08/01 09:52
L321	1	"6730998".pn.	USPAT	OR	ON	2006/08/01 09:52
L322	1	multi with layer$3 near3 heat adj sink with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L323	1	"4,575,700".pn.	USPAT; USOCR	OR	ON	2006/08/01 09:52
L324	1	1998-062476.NRAN.	DERWENT	OR	ON	2006/08/01 09:52

L325	1	heat with sink with made with (ceramic glass)with desirable	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L326	1	2000-117261.NRAN.	DERWENT	OR	ON	2006/08/01 09:52
L327	1	2001-524823.NRAN.	DERWENT	OR	ON	2006/08/01 09:52
L328	1	"6730998".pn.	USPAT	OR	ON	2006/08/01 09:52
L329	1	multi with layer$3 near3 heat adj sink with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L330	1	"4,575,700".pn.	USPAT; USOCR	OR	ON	2006/08/01 09:52
L331	8	("5029638"| "5466970"| "5506752" | "5559674"| "5706169"| "5991152").PN. OR ("6640882"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L332	52	("2414801"| "3205936"| "3372733" | "3388739"| "3413532"| "3457988" | "4092697"| "4141030"| "4158719" | "4340902"| "4345267"| "4396935" | "4404582"| "4471837"| "4535384" | "4563725"| "4587550"| "4669535" | "4729061"| "4733293"| "4788627" | "4803546"| "4810289"| "4849856" | "4849857"| "4890194"| "4909841" | "4941067"| "4954170"| "4996629" | "5012386"| "5057903"| "5172301" | "5175612"| "5227663"| "5293930" | "5310520"| "5410451"| "5514327" | "5654587"| "5693981").PN. OR ("5963795").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L333	22	("4810289"| "4830820"| "4909841" | "4926242"| "4954170"| "5049184" | "5057903"| "5152959"| "5175612" | "5310520").PN. OR ("5514327"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L334	364	heat near2 sink with channels near4 air	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L335	5	L334 and "438"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52

L336	27	("4092697" | "4158719" | "4733293" | "4788627" | "4810289" | "4909841" | "4954170" | "5057903" | "5105259" | "5105429" | "5172301" | "5175612" | "5285350" | "5291064" | "5310520" | "5485037" | "5514327" | "5552634" | "5567986").PN. OR ("5869891"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L337	2	"5701034".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L338	2	"6661087".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L339	6	silicone near2 grease with adhesive with heat near2 sink	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L340	43	L242 not L339	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L341	49	silicone near2 grease with adhesive and heat near2 sink	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L342	65	("3846824" | "4326238" | "4626961" | "4709301" | "4764845" | "4782893" | "4869954" | "4931479" | "4965699" | "4971633" | "4974119" | "4979074" | "5060114" | "5137959" | "5194480" | "5213868" | "5225265" | "5298791" | "5321582" | "5518758" | "5661902").PN. OR ("5781412"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L343	27	("4838347" | "4974119" | "5137959" | "5781412" | "5931222" | "5978223" | "5989459" | "6020424" | "6054198" | "6096414" | "6162663" | "6188576" | "6204303" | "6210520" | "6218730" | "6238596" | "6311769" | "6469379").PN. OR ("6597575"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52

L344	90	("2311526"| "3332055"| "3609104" | "4299715"| "4384610"| "4389340" | "4466483"| "4473113"| "4487856" | "4533685"| "4546411"| "4561011" | "4575432"| "4722960"| "4755249" | "4764845"| "4782893"| "4855002" | "4869954"| "4915167"| "4965699" | "4974119"| "4979074"| "5052481" | "5137959"| "5194480"| "5213868" | "5298791"| "5302344"| "5321882" | "5352731"| "5602221"| "5770318" | "5796582"| "5798171").PN. OR ("6054198").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L345	2	"5693981".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L346	2	"5693981".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L347	3	heat with sink with made with (ceramic glass) with improve	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L348	6	heat near2 sink with made with (ceramic glass) with cost	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L349	78	heat near2 sink with made with layer with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L350	11	heat near2 sink with sheet with secured with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L351	45	heat near2 sink with layer with secured with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52

L352	3	"6730998".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L353	2	"20030002260".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L354	2	"5473512".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L355	4	("6514792" "6713856").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L356	2	("6548832").URPN.	USPAT	OR	ON	2006/08/01 09:52
L357	15	("20030020399" | "4013915" | "4826271" | "4935665" | "5177593" | "5226723" | "5294487" | "5298768" | "5534718" | "6121637" | "6274890" | "6429464" | "6483161" | "6501103" | "6548832").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L358	4	("6677222" "6506669").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L359	6	("4876360" | "4897360" | "5077233" | "5264072" | "5663077" | "5756364").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L360	112	("5701034").URPN.	USPAT	OR	ON	2006/08/01 09:52
L361	17	(US-5278446-$ or US-5514327-$ or US-5597034-$ or US-5661638-$ or US-5693981-$ or US-5963795-$ or US-6054198-$ or US-6175497-$ or US-6583438-$ or US-6597575-$ or US-6617199-$ or US-6620515-$ or US-6631756-$ or US-6640882-$ or US-6644395-$ or US-6659169-$ or US-6686532-$ or US-6740972-$ or US-6778394-$ or US-6783692-$ or US-6815486-$).did.	USPAT	OR	ON	2006/08/01 09:52

L362	77	("4047198" | "4561011" | "4612601" | "4748538").PN. OR ("5291064"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L363	932	L258 and air	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L364	76	L363 and coil	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L365	77	("4047198" | "4561011" | "4612601" | "4748538").PN. OR ("5291064"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L366	27	("4092697" | "4158719" | "4733293" | "4788627" | "4810289" | "4909841" | "4954170" | "5057903" | "5105259" | "5105429" | "5172301" | "5175612" | "5285350" | "5291064" | "5310520" | "5485037" | "5514327" | "5552634" | "5567986").PN. OR ("5869891"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L367	2	"5,693,981".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L368	11	heat adj sink with sintered with binder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L369	27	heat adj sink same sintered with binder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L370	16	L369 not L368	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52

L371	55	L259 not L368	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L372	2	"5,814,536".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L373	8	heat with sink with layered with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L374	21	heat adj sink with layer$3 with adhesive with improve and (semiconductor IC chip die wafer integrated adj cirucit silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L375	63	(IC chip die wafer integrated adj circuit semiconductor) same processor with waveguide	USPAT	OR	ON	2006/08/01 09:52
L376	6	(IC chip die wafer integrated adj circuit semiconductor)and processor with coplanar near2 waveguide	USPAT	OR	ON	2006/08/01 09:52
L377	65	(IC chip die wafer integrated adj circuit semiconductor)and processor and coplanar near2 waveguide	USPAT	OR	ON	2006/08/01 09:52
L378	9	("5548150" | "5736749" | "5773353" | "6013933" | "6021675" | "6153489" | "6376859" | "6407441" | "6452249").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L379	10	("3948583" | "4912533" | "5054871" | "5182787" | "5185830" | "5282071" | "5522005" | "5621837" | "5721801").PN. OR ("6108477"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L380	86	integrated adj circuit with commonly with processor	USPAT; USOCR	OR	ON	2006/08/01 09:52
L381	3	signal with coplanar with microprocessor	USPAT; USOCR	OR	ON	2006/08/01 09:52
L382	6	processor with coplanar with waveguide	USPAT; USOCR	OR	ON	2006/08/01 09:52
L383	86	processor with waveguide with system	USPAT; USOCR	OR	ON	2006/08/01 09:52
L384	125	coplanar adj waveguide and (processor or microprocessor)	USPAT; USOCR	OR	ON	2006/08/01 09:52

L385	2	("5895971").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L386	67	("4526646"|"4543659"|"4736437"|"4863538"|"4899921"|"4944817"|"5017753"|"5059559"|"5088047"|"5113565"|"5132143"|"5145099"|"5155321"|"5155324"|"5156697"|"5173220"|"5182170"|"5238174"|"5252264"|"5264061"|"5278442"|"5284695"|"5288698"|"5304329"|"5316580"|"5325265"|"5332051"|"5342919"|"5352405"|"5385780"|"5430666"|"5463227"|"5471310"|"5484314"|"5506684"|"5516023"|"5516026"|"5527877"|"5644245"|"5645937"|"5648450"|"5672312"|"5673258"|"5693981"|"5705117"|"5733497"|"5749041"|"5814536"|"5814536"|"5817206"|"5895971"|"5900670"|"5981085"|"6015722"|"6019165"|"6111313"|"6175497"|"6251488"|"6259962"|"6268584"|"6274922"|"6296493"|"6391251"|"6457515"|"6468891"|"6529379"|"6658314"|"6730998").PN.	USPAT	OR	ON	2006/08/01 09:52
L387	8	("5029638"| "5466970"| "5506752"| "5559674"| "5706169"| "5991152").PN. OR ("6640882"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L388	52	("2414801"| "3205936"| "3372733"| "3388739"| "3413532"| "3457988"| "4092697"| "4141030"| "4158719"| "4340902"| "4345267"| "4396935"| "4404582"| "4471837"| "4535384"| "4563725"| "4587550"| "4669535"| "4729061"| "4733293"| "4788627"| "4803546"| "4810289"| "4849856"| "4849857"| "4890194"| "4909841"| "4941067"| "4954170"| "4996629"| "5012386"| "5057903"| "5172301"| "5175612"| "5227663"| "5293930"| "5310520"| "5410451"| "5514327"| "5654587"| "5693981").PN. OR ("5963795").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L389	22	("4810289"| "4830820"| "4909841"| "4926242"| "4954170"| "5049184"| "5057903"| "5152959"| "5175612"| "5310520").PN. OR ("5514327"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52

L390	5	L315 and "438"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L391	27	("4092697" | "4158719" | "4733293" | "4788627" | "4810289" | "4909841" | "4954170" | "5057903" | "5105259" | "5105429" | "5172301" | "5175612" | "5285350" | "5291064" | "5310520" | "5485037" | "5514327" | "5552634" | "5567986").PN. OR ("5869891"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L392	2	"5701034".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L393	2	"6661087".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L394	6	silicone near2 grease with adhesive with heat near2 sink	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L395	43	L283 not L394	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L396	49	silicone near2 grease with adhesive and heat near2 sink	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L397	65	("3846824" | "4326238" | "4626961" | "4709301" | "4764845" | "4782893" | "4869954" | "4931479" | "4965699" | "4971633" | "4974119" | "4979074" | "5060114" | "5137959" | "5194480" | "5213868" | "5225265" | "5298791" | "5321582" | "5518758" | "5661902").PN. OR ("5781412"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52

L398	27	("4838347" | "4974119" | "5137959" | "5781412" | "5931222" | "5978223" | "5989459" | "6020424" | "6054198" | "6096414" | "6162663" | "6188576" | "6204303" | "6210520" | "6218730" | "6238596" | "6311769" | "6469379").PN. OR ("6597575").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L399	90	("2311526" | "3332055" | "3609104" | "4299715" | "4384610" | "4389340" | "4466483" | "4473113" | "4487856" | "4533685" | "4546411" | "4561011" | "4575432" | "4722960" | "4755249" | "4764845" | "4782893" | "4855002" | "4869954" | "4915167" | "4965699" | "4974119" | "4979074" | "5052481" | "5137959" | "5194480" | "5213868" | "5298791" | "5302344" | "5321882" | "5352731" | "5602221" | "5770318" | "5796582" | "5798171").PN. OR ("6054198").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:52
L400	2	"5693981".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L401	2	"5693981".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L402	3	heat with sink with made with (ceramic glass) with improve	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L403	6	heat near2 sink with made with (ceramic glass) with cost	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L404	78	heat near2 sink with made with layer with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52

L405	11	heat near2 sink with sheet with secured with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L406	45	heat near2 sink with layer with secured with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:52
L407	3	"6730998".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L408	2	"20030002260".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L409	2	"5473512".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L410	4	("6514792" "6713856").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L411	2	("6548832").URPN.	USPAT	OR	ON	2006/08/01 09:53
L412	15	("20030020399" | "4013915" | "4826271" | "4935665" | "5177593" | "5226723" | "5294487" | "5298768" | "5534718" | "6121637" | "6274890" | "6429464" | "6483161" | "6501103" | "6548832").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:53
L413	4	("6677222" "6506669").pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L414	6	("4876360" | "4897360" | "5077233" | "5264072" | "5663077" | "5756364").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:53
L415	112	("5701034").URPN.	USPAT	OR	ON	2006/08/01 09:53

L416	17	(US-5278446-$ or US-5514327-$ or US-5597034-$ or US-5661638-$ or US-5693981-$ or US-5963795-$ or US-6054198-$ or US-6175497-$ or US-6583438-$ or US-6597575-$ or US-6617199-$ or US-6620515-$ or US-6631756-$ or US-6640882-$ or US-6644395-$ or US-6659169-$ or US-6686532-$ or US-6740972-$ or US-6778394-$ or US-6783692-$ or US-6815486-$).did.	USPAT	OR	ON	2006/08/01 09:53
L417	77	("4047198" | "4561011" | "4612601" | "4748538").PN. OR ("5291064"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:53
L418	76	L316 and coil	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L419	77	("4047198" | "4561011" | "4612601" | "4748538").PN. OR ("5291064"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:53
L420	27	("4092697" | "4158719" | "4733293" | "4788627" | "4810289" | "4909841" | "4954170" | "5057903" | "5105259" | "5105429" | "5172301" | "5175612" | "5285350" | "5291064" | "5310520" | "5485037" | "5514327" | "5552634" | "5567986").PN. OR ("5869891"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:53
L421	2	"5,693,981".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L422	11	heat adj sink with sintered with binder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L423	27	heat adj sink same sintered with binder	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L424	16	L423 not L422	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53

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L425	55	L300 not L422	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L426	2	"5,814,536".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L427	8	heat with sink with layered with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L428	21	heat adj sink with layer$3 with adhesive with improve and (semiconductor IC chip die wafer integrated adj cirucit silicon)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L429	34	heat adj sink with multi with layer$3 with adhesive and L301	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L430	63	(IC chip die wafer integrated adj. circuit semiconductor) same processor with waveguide	USPAT	OR	ON	2006/08/01 09:53
L431	6	(IC chip die wafer integrated adj circuit semiconductor)and processor with coplanar near2 waveguide	USPAT	OR	ON	2006/08/01 09:53
L432	65	(IC chip die wafer integrated adj circuit semiconductor)and processor and coplanar near2 waveguide	USPAT	OR	ON	2006/08/01 09:53
L433	9	("5548150" | "5736749" | "5773353" | "6013933" | "6021675" | "6153489" | "6376859" | "6407441" | "6452249").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:53
L434	10	("3948583" | "4912533" | "5054871" | "5182787" | "5185830" | "5282071" | "5522005" | "5621837" | "5721801").PN. OR ("6108477"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:53
L435	86	integrated adj circuit with commonly with processor	USPAT; USOCR	OR	ON	2006/08/01 09:53
L436	3	signal with coplanar with microprocessor	USPAT; USOCR	OR	ON	2006/08/01 09:53

L437	6	processor with coplanar with waveguide	USPAT; USOCR	OR	ON	2006/08/01 09:53
L438	86	processor with waveguide with system	USPAT; USOCR	OR	ON	2006/08/01 09:53
L439	125	coplanar adj waveguide and (processor or microprocessor)	USPAT; USOCR	OR	ON	2006/08/01 09:53
L440	2	("5895971").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L441	67	("4526646"|"4543659"|"4736437"|"4863538"|"4899921"|"4944817"|"5017753"|"5059559"|"5088047"|"5113565"|"5132143"|"5145099"|"5155321"|"5155324"|"5156697"|"5173220"|"5182170"|"5238174"|"5252264"|"5264061"|"5278442"|"5284695"|"5288698"|"5304329"|"5316580"|"5325265"|"5332051"|"5342919"|"5352405"|"5385780"|"5430666"|"5463227"|"5471310"|"5484314"|"5506684"|"5516023"|"5516026"|"5527877"|"5644245"|"5645937"|"5648450"|"5672312"|"5673258"|"5693981"|"5705117"|"5733497"|"5749041"|"5814536"|"5814536"|"5817206"|"5895971"|"5900670"|"5981085"|"6015722"|"6019165"|"6111313"|"6175497"|"6251488"|"6259962"|"6268584"|"6274922"|"6296493"|"6391251"|"6457515"|"6468891"|"6529379"|"6658314"|"6730998").PN.	USPAT	OR	ON	2006/08/01 09:53
L442	130	L334 and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L443	146	("3564352"| "3838984"| "4074342"| "4105861"| "4168507"| "4410927"| "4461924"| "4480262"| "4594770"| "4680613"| "4701999"| "4737395"| "4769344"| "4773955"| "4835120"| "4868349"| "4872047"| "4888449"| "4890152"| "4891687"| "4943844"| "4949220"| "4974057"| "4975761"| "4994897"| "4994936"| "5041902"| "5102828"| "5172214"| "5202288"| "5235211"| "5278446"| "5294828").PN. OR ("5701034"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:53

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L444	149	and$1j$1r.xa.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L445	103	("4863538"|"4944817"|"5017753"|"5088047"|"5132143"|"5155321"|"5155324"|"5156697"|"5173220"|"5182170"|"5252264"|"5264061"|"5278442"|"5284695"|"5304329"|"5316580"|"5325265"|"5332051"|"5342919"|"5352405"|"5385780"|"5484314"|"5527877"|"5648450"|"5672312"|"5673258"|"5705117"|"5733497"|"5749041"|"5814536"|"5817206"|"5900670"|"5981085"|"6015722"|"6296493"|"6468891"|"4526646"|"4543659"|"4736437"|"4899921"|"5059559"|"5113565"|"5145099"|"5238174"|"5288698"|"5430666"|"5463227"|"5471310"|"5506684"|"5516023"|"5516026"|"5644245").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L446	123	L445 L251 L252 L253	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L447	112	fin with heat with sink with improve	USPAT	OR	ON	2006/08/01 09:53
L448	199	heat adj sink near3 layer$3 with adhesive	USPAT	OR	ON	2006/08/01 09:53
L449	134	("4526646"|"4543659"|"4736437"|"4863538"|"4899921"|"4944817"|"5017753"|"5059559"|"5088047"|"5113565"|"5132143"|"5145099"|"5155321"|"5155324"|"5156697"|"5173220"|"5182170"|"5238174"|"5252264"|"5264061"|"5278442"|"5284695"|"5288698"|"5304329"|"5316580"|"5325265"|"5332051"|"5342919"|"5352405"|"5385780"|"5430666"|"5463227"|"5471310"|"5484314"|"5506684"|"5516023"|"5516026"|"5527877"|"5644245"|"5645937"|"5648450"|"5672312"|"5673258"|"5693981"|"5705117"|"5733497"|"5749041"|"5814536"|"5817206"|"5895971"|"5900670"|"5981085"|"6015722"|"6019165"|"6111313"|"6175497"|"6251488"|"6259962"|"6268584"|"6274922"|"6296493"|"6391251"|"6457515"|"6468891"|"6529379"|"6658314"|"6730998").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53

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L450	130	L315 and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L451	146	("3564352" | "3838984" | "4074342" | "4105861" | "4168507" | "4410927" | "4461924" | "4480262" | "4594770" | "4680613" | "4701999" | "4737395" | "4769344" | "4773955" | "4835120" | "4868349" | "4872047" | "4888449" | "4890152" | "4891687" | "4943844" | "4949220" | "4974057" | "4975761" | "4994897" | "4994936" | "5041902" | "5102828" | "5172214" | "5202288" | "5235211" | "5278446" | "5294828").PN. OR ("5701034"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/08/01 09:53
L452	149	and$1j$1r.xa.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L453	103	("4863538"|"4944817"|"5017753"|"5088047"|"5132143"|"5155321"|"5155324"|"5156697"|"5173220"|"5182170"|"5252264"|"5264061"|"5278442" |"5284695"|"5304329"|"5316580"|"5325265"|"5332051"|"5342919"|"5352405"|"5385780"|"5484314"|"5527877"|"5648450"|"5672312"|"5673258" |"5705117"|"5733497"|"5749041"|"5814536"|"5817206"|"5900670"|"5981085"|"6015722"|"6296493"|"6468891"|"4526646"|"4543659"|"4736437" |"4899921"|"5059559"|"5113565"|"5145099"|"5238174"|"5288698"|"5430666"|"5463227"|"5471310"|"5506684"|"5516023"|"5516026"|"5644245").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L454	123	L453 L292 L293 L294	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L455	112	fin with heat with sink with improve	USPAT	OR	ON	2006/08/01 09:53
L456	199	heat adj sink near3 layer$3 with adhesive	USPAT	OR	ON	2006/08/01 09:53

L457	134	("4526646"|"4543659"|"4736437"|"4863538"|"4899921"|"4944817"|"5017753"|"5059559"|"5088047"|"5113565"|"5132143"|"5145099"|"5155321"|"5155324"|"5156697"|"5173220"|"5182170"|"5238174"|"5252264"|"5264061"|"5278442"|"5284695"|"5288698"|"5304329"|"5316580"|"5325265"|"5332051"|"5342919"|"5352405"|"5385780"|"5430666"|"5463227"|"5471310"|"5484314"|"5506684"|"5516023"|"5516026"|"5527877"|"5644245"|"5645937"|"5648450"|"5672312"|"5673258"|"5693981"|"5705117"|"5733497"|"5749041"|"5814536"|"5814536"|"5817206"|"5895971"|"5900670"|"5981085"|"6015722"|"6019165"|"6111313"|"6175497"|"6251488"|"6259962"|"6268584"|"6274922"|"6296493"|"6391251"|"6457515"|"6468891"|"6529379"|"6658314"|"6730998"). PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L458	264	L239 and heat near2 (sink spreader) near3 channel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L459	247	heat with sink with made with (ceramic glass) and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L460	297	heat adj sink near3 layer$3 with adhesive	US-PGPUB; USPAT	OR	ON	2006/08/01 09:53
L461	264	L280 and heat near2 (sink spreader) near3 channel	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L462	247	heat with sink with made with (ceramic glass) and "257"/$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L463	297	heat adj sink near3 layer$3 with adhesive	US-PGPUB; USPAT	OR	ON	2006/08/01 09:53
L464	405	L237 and "257"/$.ccls.	USPAT	OR	ON	2006/08/01 09:53

L465	404	heat adj sink near3 layer$3 with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L466	405	L278 and "257"/$.ccls.	USPAT	OR	ON	2006/08/01 09:53
L467	364	heat near2 sink with channels near4 air	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L468	404	heat adj sink near3 layer$3 with adhesive	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L469	2051	L235 and "257"/$.ccls.	USPAT	OR	ON	2006/08/01 09:53
L470	2051	L276 and "257"/$.ccls.	USPAT	OR	ON	2006/08/01 09:53
L471	488	method with orientation with crystal with axis	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L472	117	(method with orientation with crystal with axis).clm.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53
L473	2	"6,019,165".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/01 09:53